

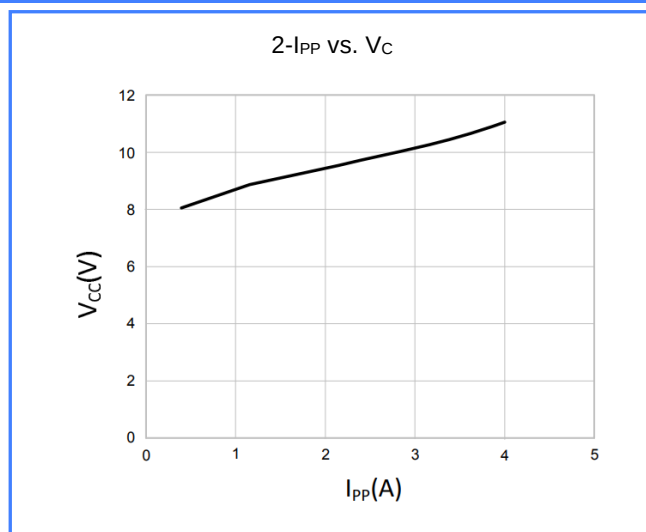
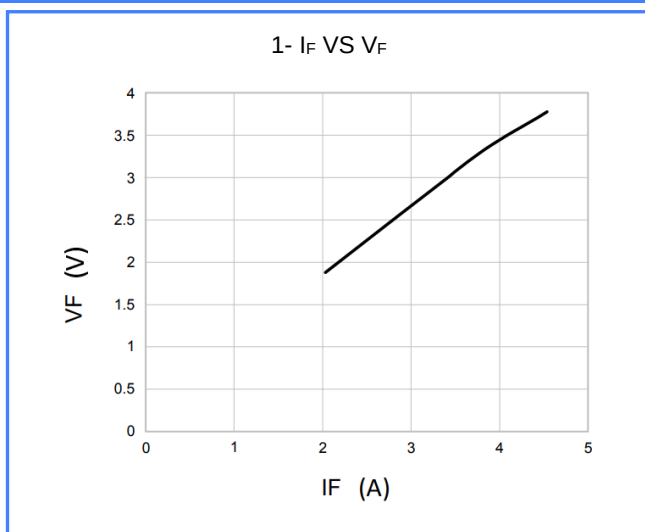
Absolute Maximum Ratings($T_{amb}=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	P_{PP}	100	Watts
Peak Current (8/20 μs)	I_{PP}	5	A
ESD per IEC 61000-4-2 (Air)	V_{ESD}	± 15	KV
ESD per IEC 61000-4-2 (Contact)		± 12	KV
Operating Temperature Range	T_J	-55 to +125	$^{\circ}\text{C}$
Storage Temperature Range	T_{STJ}	-55 to +150	$^{\circ}\text{C}$
Lead Soldering Temperature	T_L	260(10sec)	$^{\circ}\text{C}$

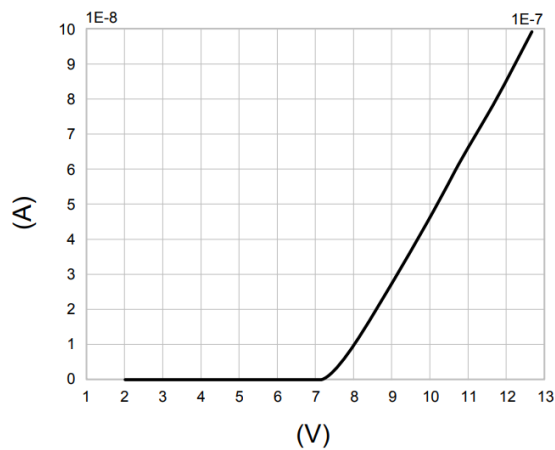
Electrical Characteristics ($T_A = 25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V_{RRM}				5	V
Forward voltage	V_{F1}	$I_F=1\text{mA}$	0.4	0.8	1.5	V
Forward voltage	V_{F2}	$I_F=1\text{A}$		1.8		V
Breakdown Voltage	V_{BR}	$I_T = 1\text{mA}$	6.0	7.0		V
Reverse Leakage Current	I_R	$V_{RWM} = 5\text{V}$		0.03	1	μA
Clamping Voltage	V_C	$I_{PP} = 1\text{A}$ (8/20 μs pulse)		8.5	12.0	V
Junction Capacitance	C_{J1}	$V = 0\text{V}$, $f = 1\text{MHz}$ Between I/O pins		0.35	0.45	pF
Junction Capacitance	C_{J2}	$V = 0\text{V}$, $f = 1\text{MHz}$ Any I/O pin to GND		0.6	0.65	pF

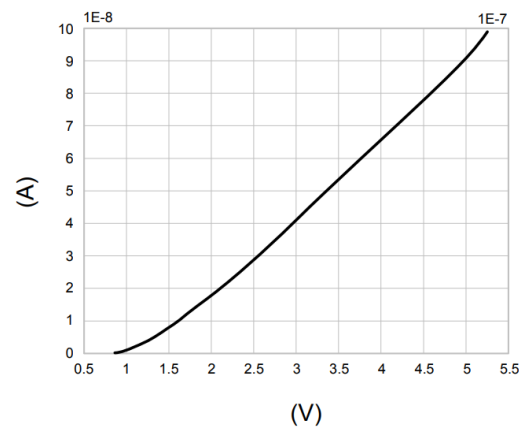
Characteristics Curves ($T_A=25^{\circ}\text{C}$ unless otherwise Specified)



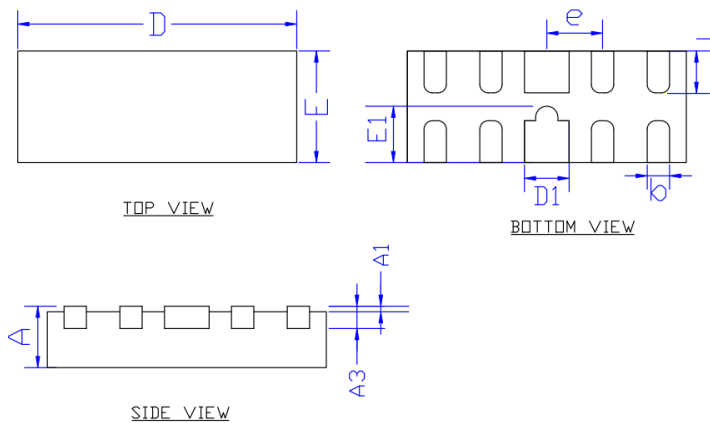
3- Positive Transmission Line Pulsing (TLP) Plot



4- Negative Transmission Line Pulsing (TLP) Plot



PACKAGE OUTLINE DIMENSIONS(DFN2510-10L)



Symbol	mm		
	MIN.	NOM.	MAX.
A	0.500	-	0.600
A1	0.000	-	0.050
A3	0.127REF.		
D	2.450	2.500	2.550
E	0.950	1.000	1.050
D1	0.350	0.400	0.450
E1	0.460	0.510	0.560
b	0.150	0.200	0.250
L	0.330	0.380	0.430
e	0.500		

Disclaimer

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.